

#2/A  
P.B.  
4/30/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :  
Kazuhiro OTSU et al. :  
Serial No. [NEW] : Attn: Application Branch  
Filed February 7, 2002 : Attorney Docket No. 2002-0208A

SEPARATING MACHINE FOR THINNED  
SEMICONDUCTOR SUBSTRATE AND  
SEPARATION METHOD

THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEE FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975.

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,  
Washington, DC 20231

Sir:

In the interest of compact prosecution and to reduce PTO filing fees, please amend the  
present application as follows:

IN THE CLAIMS:

*Please rewrite claim 4 as follows:*

4. (Amended) A separating machine for a thinned semiconductor substrate according to  
claim 2, wherein the system for making a starting point for the separation is a system of pressing  
with a knife edge.

*Please add the following new claim:*

9. (New) A separating machine for a thinned semiconductor substrate according to claim  
3, wherein the system for making a starting point for the separation is a system of pressing with a  
knife edge.